ULTRA THIN BODY 18nm SOI N-MOSFET (The Effect of Sidewall Spacer Oxide Thickness to the Device Performance)

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This Report Is Submitted In Partial Fulfillment of Requirements For The Bachelor Degree of Electronic Engineering (Computer Engineering)

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To my beloved family

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ABSTRACT

This research focus on Ultra-Thin Body Silicon On Insulator (UTB SOI) which is fully depleted. The structure is an improvement from the conventional MOSFET which further improve the performance of the device. UTB SOI is much preferred than conventional MOSFET because of thinner body thickness, smaller leakage current and able to improve power consumption. This research project is focus on the design of UTB SOI device which can be scaled down to 18nm with 5.8nm body thickness. The metal gate is used for the gate known as titanium instead of polysillicon gate. It is much more ideal for charging and discharging the gate capacitance of the transistor and resulting in faster operating circuit. Furthermore, the utilization of metal gate is important to get the smallest value of gate resistance near to 0 and able to reduce leakage current. This research also includes the effect of sidewall spacer oxide thickness variation on the UTB SOI performance. Athena and Atlas of Silvaco Simulator have been used to design and simulate in order to obtain the result of MOSFET structure, IV characteristic, the leakage current, the drive current and the sub threshold slope.

ABSTRAK

Kajian ini tertumpu kepada Ultra Thin Body Silicon On Insulator (UTB SOI) untuk Fully Depleted. Strukturnya adalah penambah-baikan daripada MOSFET konvensional yang memperbaiki lagi prestasi peranti tersebut. UTB SOI lebih diutamakan berbanding MOSFET konvensional kerana kenipisan ketebalan badannya, kebocoran arus yang lebih kecil dan mampu untuk meningkatkan penggunaan kuasa. Kajian projek ini fokus kepada reka bentuk UTB SOI yang boleh diskala kecilkan sehingga 18nm dengan 5.8nm ketebalan badannya. Metal gate yang digunakan sebagai metal dikenali sebagai titanium berbanding menggunakan metal polisilikon. Ianya lebih sesuai untuk mengecas dan menyahcas gate capacitance transistor dan menyebabkan operasi litar yang lebih laju. Tambahan pula, penggunaan metal gate sangat penting untuk mendapatkan nilai gate resistance yang terkecil yang menghampiri 0 dan mampu mengurangkan kebocoran arus. Kajian ini juga merangkumi kesan variasi ketebalan sidewall spacer oxide kepada prestasi UTB SOI. Athena dan Atlas (Simulator Silvaco) telah digunakan untuk merekabentuk dan mensimulasikannya untuk mendapatkan hasil struktur MOSFET, ciri-ciri IV, kebocoran arus, pemanduan arus dan sub-threshold slope.

CONTENTS

CHAPTER	TITLE	PAGE
	PROJECT TITLE	i
	REPORT STATUS VERIFICATION FORM	ii
	DECLARATION	iii
	SUPERVISOR DECLARATION	iv
	DEDICATION	V
	ACKNOWLEDGMENT	vi
	ABSTRACT	vii
	ABSTRAK	viii
	CONTENTS	ix
	LIST OF TABLES	xiii
	LIST OF FIGURES	xiv
	ABBREVIATIONS	xvii
	LIST OF SYMBOLS	xviii
	LIST OF APPENDICES	xix

I INTRODUCTION

1.1	Introduction of the Project	1
1.2	Objectives	2
1.3	Problem Statement	2
1.4	Scope of the Project	2
1.5	Importance of the Project	3
1.6	Project Outline	4

II LITERATURE REVIEW

2.1	Introd	uction	5
2.2	Backg	round Studies	6
	2.2.1	Ultra Thin Body Silicon On-Insulator	
		(UTB SOI)	6
	2.2.2	Short Channel Effect in MOSFET	7
	2.2.3	Floating Body Effect in SOI Technology	9
	2.2.4	Effects of Gate Sidewall Spacer Thickness	9
	2.2.5	SOI vs Bulk Technology	10
	2.2.6	ITRS Projection on Fully Depleted SOI for	
		Next Generation	12

III METHODOLOGY

3.1	Introd	uction	15
3.2	Flowc	hart of the Project	16
3.3	Simula	ation Using Silvaco TCAD	17
	3.3.1	ATHENA	17
	3.3.2	ATLAS	18
	3.3.3	Deckbuild	18
	3.3.4	Tonyplot	18
3.4	Step E	By Step of Device Simulation	19

IV RESULTS AND DISCUSSION

4.1	Introduction	
4.2	Specifications of the Device Based on ITRS	30
4.3	Results of 4nm Spacer Oxide	31
	4.3.1 Ultra Thin Body Structure	31

Х

	4.3.2	Graph Transfer Curve for High Drain	
		Voltage (0.82V)	32
	4.3.3	Graph Transfer Curve for Low Drain	
		Voltage (0.05V)	34
	4.3.4	Overlay Graph of High Drain and Low	
		Drain Voltage	36
4.4	Result	ts of 6nm Spacer Oxide	37
	4.4.1	Ultra Thin Body Structure	37
	4.4.2	Graph Transfer Curve for High Drain	
		Voltage (0.82V)	38
	4.4.3	Graph Transfer Curve for Low Drain	
		Voltage (0.05V)	40
	4.4.4	Overlay Graph of High Drain and Low	
		Drain Voltage	42
4.5	Result	ts of 8nm Spacer Oxide	43
	4.3.1	Ultra Thin Body Structure	43
	4.3.2	Graph Transfer Curve for High Drain	
		Voltage (0.82V)	44
	4.3.3	Graph Transfer Curve for Low Drain	
		Voltage (0.05V)	46
	4.3.4	Overlay Graph of High Drain and Low	
		Drain Voltage	48
4.6	Comp	arison of Results	49

V CONCLUSION AND RECOMMENDATIONS

5.1	Conclusion	52
5.2	Recommendations	54

REFERENCES	55
APPENDIX A	59
APPENDIX B	62
APPENDIX C	65
APPENDIX D	68

LIST OF TABLES

TABLE TITLE

PAGE

2.1	The long term year (2010-2024) projections of some	
	critical parameters for UTB-FD, low power operation	13
4.1	Specifications of the Design	30
4.2	Comparison of ITRS Value and Experimental Value	49

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LIST OF FIGURES

FIGURE TITLE

PAGE

1.1	Logo of Silvaco and ITRS	3
2.1	Ultra-Thin Body Structure	6
2.2	DIBL Effect	8
2.3	UTB device structure with spacer sidewall oxide	10
2.4	Bulk NMOS Transistor vs SOI NMOS Transistor	11
2.5	Comparison of Bulk CMOS and SOI CMOS	12
3.1	Flowchart of the project	16
3.2	Simulation Flowchart using Silvaco TCAD	17
3.3	Creating an initial structure	19
3.4	Deposition of BOX layer	20
3.5	Deposition of Silicon layer	20
3.6	Mask layer formation	21
3.7	Etching certain region of Oxide	21
3.8	Threshold Voltage Adjust Implant	22
3.9	Etching mask layer	22
3.10	EOT deposition	23
3.11	Metal Gate Deposition	23
3.12	Set the gate length	24
3.13	Spacer Oxide Deposition	24
3.14	Sidewall Spacer Oxide Etching	25
3.15	Etching oxide to form open contact window	25
3.16	Aluminum Deposition	26
3.17	Etching unwanted Aluminum	26

3.18	Mirror Right	27
3.19	Specify the electrode name	27
3.20	Smaller thickness of Spacer Oxide	28
3.21	Bigger thickness of Spacer Oxide	28
4.1	Ultra-Thin Body Structure	31
4.2	Ultra-Thin Body Structure with contour and electrodes	31
4.3	Linear Graph	32
4.4	Log Graph	32
4.5	Linear + Log Graph	33
4.6	Linear Graph	34
4.7	Log Graph	34
4.8	Linear + Log Graph	35
4.9	Overlay Graph of Linear	36
4.10	Overlay Graph of Log	36
4.11	Ultra-Thin Body Structure	37
4.12	Ultra-Thin Body Structure with contour and electrodes	37
4.13	Linear Graph	38
4.14	Log Graph	38
4.15	Linear + Log Graph	39
4.16	Linear Graph	40
4.17	Log Graph	40
4.18	Linear + Log Graph	41
4.19	Overlay Graph of Linear	42
4.20	Overlay Graph of Log	42
4.21	Ultra-Thin Body Structure	43
4.22	Ultra-Thin Body Structure with contour and electrodes	43
4.23	Linear Graph	44
4.24	Log Graph	44
4.25	Linear + Log Graph	45
4.26	Linear Graph	46

4.27	Log Graph	46
4.28	Linear + Log Graph	47
4.29	Overlay Graph of Linear	48
4.30	Overlay Graph of Log	48
4.31	Comparison of ON current between high drain and	
	low drain	50
4.32	Comparison of OFF current between high drain and	
	low drain	51

ABBREVIATIONS

MOSFET	-	Metal Oxide Semiconductor Field Effect Transistor
nm	-	Nanometer
ITRS	-	International Technology Roadmap for Semiconductor
TCAD	-	Technology Computer Aided Design
VLSI	-	Very Large Scale Integrated Circuits
NMOS	-	N-Channel MOSFET
UTB	-	Ultra Thin Body
SOI	-	Silicon On Insulator
SS	-	Sub-threshold Slope
RF	-	Radio Frequency
IC	-	Integrated Circuit

xvii

LIST OF SYMBOLS

ID	-	Drain Current
V _D	-	Drain Voltage
V _{GS}	-	Gate-To-Source Voltage
V_{TH}	-	Threshold Voltage
L _G	-	Gate Length
I _{ON}	-	Drive Current
I _{OFF}	-	Leakage Current
SS	-	Sub-threshold Swing

xviii

LIST OF APPENDICES

NO	TITLE	PAGE
А	ATHENA INPUT FILE : Ultra-Thin Body 18nm SOI	
	N-MOSFET with 4nm length of thickness of Sidewall	
	Spacer Oxide	59
В	ATHENA INPUT FILE : Ultra-Thin Body 18nm SOI	
	N-MOSFET with 6nm length of thickness of Sidewall	
	Spacer Oxide	62
С	ATHENA INPUT FILE : Ultra-Thin Body 18nm SOI	
	N-MOSFET with 8nm length of thickness of Sidewall	
	Spacer Oxide	65
D	ATLAS INPUT FILE : Linear ID – VGS Transfer Curves	
	and Log ID – VGS Curves for High Drain Voltage $(0.82V)$)
	and Low Drain Voltage (0.05V) of All Specifications	68

CHAPTER I

INTRODUCTION

1.1 INTRODUCTION OF THE PROJECT

Fully Depleted Ultra-Thin Body Silicon On Insulator (FD UTB SOI) able to further improve the performance of the device as compared to conventional MOSFET. MOSFET is actually a type of transistor used for amplifying and switching electronic signals. It is known as the fundamental block in digital logic circuit and FD UTB SOI is one of the examples of MOSFET. It shows an improvement on its performance where it can be proven through the higher switching speed and smaller leakage current. This research was extended to see the impact of different sidewall spacer oxide thickness on the device performance. For this purpose, 3 different thickness has been chosen which are 4nm, 6nm and 8nm. So, Athena and Atlas of Silvaco Simulator have been used to complete this project in order to obtain the result of MOSFET structure, IV characteristic, the leakage current, the drive current and the sub threshold slope.

1.2 OBJECTIVES

- To design and examine the performance of Ultra Thin Body SOI 18nm N-MOSFET including IV characteristic, the leakage current, the drive current and the sub threshold slope
- To investigate the effects of gate sidewall spacer thickness on UTB SOI performance.

1.3 PROBLEM STATEMENT

- UTB control over short-channel effect which eliminate sub-surface leakage path and extend the scalability of Si CMOS technology
- Sidewall spacer oxide thickness is one of the concerns that affect the performance of the device

1.4 SCOPE OF THE PROJECT

This project is about designing FD UTB SOI through the use of Silvaco software. Under Silvaco software, Athena and Atlas are very important platform in order to obtain the result. Athena is a simulator that provides general capabilities for numerical, physically-based, two dimensional simulation of semiconductor processing. While Atlas is a modular and extensible framework for one, two and three dimensional semiconductor device simulation, it is implemented using modern software engineering practices that promote reliability, maintainability, and extensibility. So in order to complete the simulation, ITRS (International Technology Roadmap for Semiconductor) is used as a guideline and reference to design the Ultra-Thin Body SOI N-MOSFET.

- Working bench on 18nm UTBSOI with 5.8nm body thickness
- Investigating its performance
- Future study will extended to gate sidewall spacer thickness for 3 different thickness



Figure 1.1 : Logo of Silvaco and ITRS

1.5 IMPORTANCE OF PROJECT

- Ultra-thin body (UTB) silicon-on-insulator (SOI) devices have shown great potential for scaling toward channel lengths of 10 nm and below
- UTB provides much promising performance and much flexible than bulk MOSFET
- Can be used in microelectronics industry, high performance RF applications and can be used in photonics
- UTB enable the industries to design much smaller ICs but with complex functions

1.6 PROJECT OUTLINE

In chapter 1, it tells more about the background of the project as well as the purpose of doing this project. It consists of several elements such as introduction, objective, problem statement, scope and importance of the project.

For chapter 2, it is actually to define key terms, definitions and terminology that are related to the topic. This chapter is very useful to identify case studies and existing facts which can be used as supportive evidence of the research.

Chapter 3 is telling more about the project flow from the beginning till the end. In this chapter, it tells the readers about the tools or software that need to be used in order to obtain the desired outcome. As already mentioned before, there are 2 platforms that must be used which known as Athena and Atlas to obtain the results.

In chapter 4, it explains in details the results obtained for different length of Sidewall Spacer Oxide on the device. There are 3 different lengths used which are 4nm, 6nm and 8nm. Based on the results, further analysis must be performed to obtain the hypothesis and conclusion of the project.

Finally, chapter 5 is important to conclude the project based on the obtained results in chapter 4. It is important to know whether this project is successful or not depends on the achievement of objectives stated in chapter 1. Last but not least, several recommendations must be presented to improve the results in the future.

CHAPTER II

LITERATURE REVIEW

2.1 INTRODUCTION

This section describes review of previous studies that are related with this case study in much more detail. The literature review is conducting to understand the concept and also to get some ideas about the overall structure of the project.

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